

# **Pre-Release Stackup Report**

Pre-Release #: **P22464B** 

Cust: DDI - Milpitas			Total Layers: 12
Part #: ALTERA CYCLONE III HOST	Rev	Finished Thickness: 0.0730 +/- 0.0060	Finished Over: <b>All</b>
		Lam Thickness: 0.0680 +/- 0.0030	Material Type: Isola 370HR

lmp	edance Requirements:	Orig Line	Fin. Line	Ref Pln	2nd Ref Pln	Targeted Desired Impedance	Impedance Tolerance	Actual Calculated Impedance	Diff Line Centers	Diff Line Space	Original Coplanar Spacing	Finished Coplanar Spacing
1	DIF-Coated Microstrip Edg Cpld		.00400	2		100.00 Ω	+/- 10%	99.42 🗘	.01900	.01500		
1	SE-Coated Microstrip		.00425	2		50.00 Ω	+/- 10%	49.64 <i>\O</i>				
3	DIF-Stripline Edg Cpld		.00400	2	4	100.00 Ω	+/- 10%	101.01 $\Omega$	.01200	.00800		
3	SE-Stripline		.00450	2	4	50.00 Ω	+/- 10%	49.24 $\Omega$				
6	DIF-Dual Stripline Edg Cpld		.00400	5	8	100.00 Ω	+/- 10%	100.35 $\Omega$	.01400	.01000		
6	SE-Dual Stripline		.00450	5	8	50.00 Ω	+/- 10%	49.60 $\Omega$				
7	DIF-Dual Stripline Edg Cpld		.00400	8	5	100.00 Ω	+/- 10%	100.35 $\Omega$	.01400	.01000		
7	SE-Dual Stripline		.00450	8	5	50.00 Ω	+/- 10%	49.60 $\Omega$				
10	DIF-Stripline Edg Cpld		.00400	11	9	100.00 Ω	+/- 10%	101.01 $\Omega$	.01200	.00800		
10	SE-Stripline		.00450	11	9	50.00 Ω	+/- 10%	49.24 🗘				
12	DIF-Coated Microstrip Edg Cpld		.00400	11		100.00 Ω	+/- 10%	99.42 $\Omega$	.01900	.01500	·	
12	SE-Coated Microstrip		.00425	11		50.00 Ω	+/- 10%	49.64 <i>Ω</i>				

## **Controlled Impedance Notes:**

Lamination Stackup:			s and Tolerances:	Base Material Rqmts:		Dk @
L#/Type	Description:	Cu+:	Laminate/PrePreg:	Type:	Description:	1Ghz
1 Mix	Foil ( H oz )	.00060				
	Pre-Preg ( 1 x 1080 )		.0027 +/- 0.0003		Isola 370HR	3.9
2 Pln	Core 0.0040 1/H	.00120	.0040		Isola 370HR	
3 Sig	•	.00060				4.37
	Pre-Preg ( 1 x 1080 )		.0060 +/- 0.0006		Isola 370HR	4.07
	Pre-Preg (1 x 2113)					
4 Pln	Core 0.0040 1/1	.00120	.0040		Isola 370HR	
5 Pln		.00120				4.37
	Pre-Preg ( 2 x 106 )		.0030 +/- 0.0003		Isola 370HR	3.81
6 Sig	Core 0.0180 H/H	.00060	.0180		Isola 370HR	
7 Sig		.00060				4.4
	Pre-Preg ( 2 x 106 )		.0030 +/- 0.0003		Isola 370HR	3.81
8 Pln	Core 0.0040 1/1	.00120	.0040		Isola 370HR	
9 Pln		.00120				4.37
	Pre-Preg ( 1 x 2113 )		.0060 +/- 0.0006		Isola 370HR	4.07
	Pre-Preg ( 1 x 1080 )					
10 Sig	Core 0.0040 H/1	.00060	.0040		Isola 370HR	
11 Pin		.00120				4.37
	Pre-Preg ( 1 x 1080 )		.0027 +/- 0.0003		Isola 370HR	3.9
12 Mix	Foil ( H oz )	.00060				

Target Post-Lam Thickness: 0.0680 +/- 0.0030

Copper Oz Legend: H=1/2oz T=3/8oz Q=1/4oz E=1/8oz S=1/16oz

Stackup Notes:

APPROVED STACKUP MUST BE INCLUDED WITH THE DATA PACKAGE PRIOR TO MANUFACTURING

 Prepared By:
 Page 1 of 2
 Printed:
 10/05/07
 2:26 pm



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		Lam Thickness: 0.0680 +/- 0.0030	Material Type: Isola 370HR

- \* The Controlled Impedance Stackup and tables were calculated utilizing ApsimRLGC from Applied Simulation Technology
- \* Impedance value tolerances shall be +/- 10% or customer required tolerance.

Designed Artwork Spacing Requirements: (Based On Starting Copper Weight)

#### External Layers:

- \* 1/4 oz. Copper = .003 Min.
- \* 3/8 oz. Copper = .0035 Min.
- \* 1/2 oz. Copper = .004 Min.
- \* 1 oz. Copper = .005 Min.
- \* 2 oz. Copper = .007 Min.

### Internal Layers:

- \* 3/8 oz. Copper = .00325 Min.
- \* 1/2 oz. Copper = .0035 Min.
- \* 1 oz. Copper = .004 Min.
- \* 2 oz. Copper = .006 Min.

Note: Min. spacing outside of the parameters above will require DDi's engineering approval.

### Finished Copper Thickness On External Layers:

Conductor thickness calculated in RLGC includes base copper and additional copper plating (assuming hole plating requirement is .001 min.) - Finished surface conductor thickness is as follows:

- \* 1/4 oz. Base Copper + Copper Plating = .0016
- \* 3/8 oz. Base Copper + Copper Plating = .0017
- \* 1/2 oz. Base Copper + Copper Plating = .0019
- \* 1 oz. Base Copper + Copper Plating = .0024
- \* 2 oz. Base Copper + Copper Plating = .0036

Note: Soldermask thickness over the conductor calculated on RLGC is .8 mils.

* If written authorization is required, please sign b	pelow and Fax back to (408) 956-2072
Approved By:	Date: